

46. (New) The method of claim 33, wherein the first metal layer is platinum, ruthenium, or iridium and the stopping compound is a polyethylenimine.

47. (New) The system of claim 16, wherein at least one polishing additive is a polycarboxylic acid.

48. (New) The system of claim 16, wherein at least one stopping compound is a polyetheramine.

A¹⁴ 49. (New) The system of claim 16, wherein at least one oxidizing agent is a peroxide, and wherein the system further comprises at least one passivation film forming agent comprising one or more 5-6 member heterocyclic nitrogen-containing rings.

50. (New) The system of claim 24, wherein at least one polishing additive is a polycarboxylic acid.

51. (New) The system of claim 1, wherein at least one polishing additive is a carboxylic acid and at least one stopping compound has a molecular weight of about 250 or more.

REMARKS

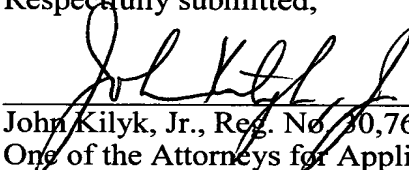
The paragraphs and tables listed above from the specification and claims 7, 9-10, 23, 25, and 43 have been amended to correct typographical errors. Newly added claims 45 and 46 are directed to a method of polishing a substrate comprising a first metal layer, which can be copper, aluminum, titanium, tungsten, platinum, ruthenium, iridium, and combinations thereof, and wherein the stopping compound is a polyethylenimine. Support for the new claims can be found in the specification at page 4, lines 11-18, and page 8, line 16, through page 9, line 9. Newly added claim 47 modifies the system of claim 16 by further specifying that the polishing additive be a polycarboxylic acid. Newly added claim 48 modifies the system of claim 16 by further specifying that the stopping compound be a polyetheramine. Support for the new claims can be found in the specification at page 7, lines 11-14, and page 8, line 36, through page 9, line 9. Newly added claim 49 modifies the system of claim 16 by further specifying that the oxidizing agent is peroxide, and that the system further comprise a passivation film-forming agent. Support for the new claim can be found in the specification at page 4, line 29, through page 5, line 5, and page 11, lines 10-28. Newly added claim 50 modifies the system of claim 24 by further specifying that the polishing additive specifically is a polycarboxylic acid. Newly added

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claim 51 modifies the system of claim 1 by further specifying that the polishing additive is a carboxylic acid and the stopping compound has a molecular weight of about 250 or more. Support for the new claims can be found in the specification at page 7, lines 11-14, and page 9, line 35, through page 10, line 5. No new matter has been added by way of these amendments. For the convenience of the Examiner, the precise changes to the specification and claims, as well as a complete set of pending claims, as amended, are set forth on separate attachments hereto.

The application is considered in good and proper form for allowance, and the Examiner is respectfully requested to pass this application to issue. If in the opinion of the Examiner a telephone conference would expedite the prosecution of the subject application, the Examiner is invited to call the undersigned attorney.

Respectfully submitted,



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CERTIFICATE OF MAILING

I hereby certify that this PRELIMINARY AMENDMENT (along with any documents referred to as being attached or enclosed) is being deposited with the United States Postal Service on the date shown below with sufficient postage as first class mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231.

Date: 1/17/2002

